Small switching (60V, 2A) 2SK3065

Features

- 1) Low on resistance.
- 2) High-speed switching.
- 3) Optimum for a pocket resource etc. because of undervoltage actuation (2.5V actuation).
- 4) Driving circuit is easy.
- 5) Easy to use parallel.
- 6) It is strong to an electrostatic discharge.

Structure

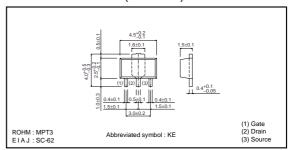
Silicon N-channel MOS FET transistor

◆Absolute maximum ratings (Ta = 25°C)

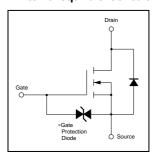
Paramete	Parameter		Limits	Unit
Drain-source voltage		Voss	60	V
Gate-source voltage		Vgss	±20	V
Drain current	Continuous	ΙD	2	А
	Pulsed	IDP*1	8	А
Reverse drain current	Continuous	IDR	2	А
	Pulsed	IDRP*1	8	А
Total power dissipation(Tc=25°C)		Pp	0.5 2*2	W
Channel temperature		Tch	150	°C
Storage temperature		Tstg	-55~+150	°C

- *1 Pw ≤ 10μs, Duty cycle ≤ 1% *2 When mounted on a 40 × 40 × 0.7 mm alumina board.

●External dimensions (Units : mm)



•Internal equivalent circuit



agate and the source to protect against static electricity when the product is in use.

Use the protection circuit when rated voltages are exceeded.

● Electrical characteristics (Ta = 25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Test Conditions
Gate-source leakage	Igss	-	-	±10	μА	Vgs = ±20V, Vps = 0V
Drain-source breakdown voltage	V _{(BR)DSS}	60	-	-	V	In = 1mA, Vgs = 0V
Zero gate voltage drain current	IDSS	-	-	10	μА	Vps = 60V, Vgs = 0V
Gate threshold voltage	V _{GS(th)}	0.8	-	1.5	V	Vps = 10V, Ip = 1mA
Static drain-source on-state resistance	RDS(on)	-	0.25	0.32	Ω	In = 1A, Vgs = 4V
	RDS(on)	-	0.35	0.45	Ω	In = 1A, Vgs = 2.5V
Forward transfer admittance	Yfs *	1.5	-	-	S	In = 1A, Vns = 10V
Input capacitance	Ciss	-	160	-	pF	Vps = 10V
Output capacitance	Coss	-	85	-	pF	Vgs=0V
Reverse transfer capacitance	Crss	-	25	-	pF	f = 1MHz
Turn-on delay time	td(on)	-	20	-	ns	In = 1A, Vnn ≒ 30V
Rise time	tr	-	50	-	ns	V _G s = 4V
Turn-off delay time	td(off)	-	120	-	ns	R _L =30Ω
Fall time	tr	_	70	_	ns	R _G = 10Ω

* Pw \leq 300 μ s, Duty cycle \leq 1%

Packaging specifications

Туре	Package	Taping
	Code	T100
	Basic ordering unit (pieces)	1000
2SK3065		0

• Electrical characteristic curves

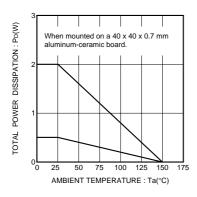


Fig.1 Total Power Dissipation vs. Case Temperature

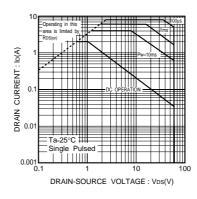


Fig.2 Maximum Safe Operating Area

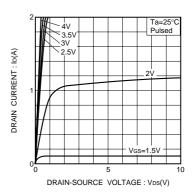


Fig.3 Typical Output Characteristics

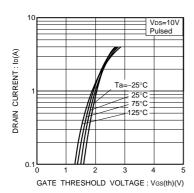


Fig.4 Typical Transfer Characteristics

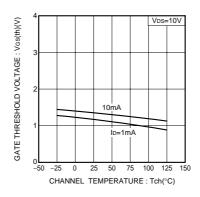


Fig.5 Gate Threshold Voltage vs. Channel Temperature

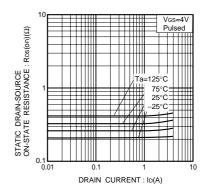
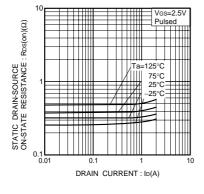
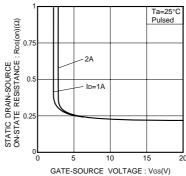


Fig.6 Static Drain-Source On-State Resistance vs. Drain Current(I)





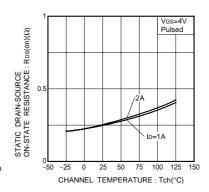
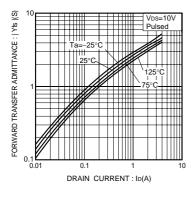
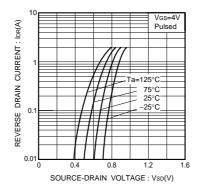


Fig.7 Static Drain-Source On-State Resistance vs. Drain Current(II)

Fig.8 Static Drain-Source On-State Resistance vs. Gate-Source Voltage

Fig.9 Static Drain-Source On-State Resistance vs. Channel Temperature





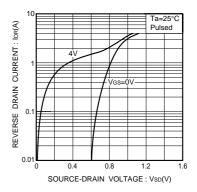
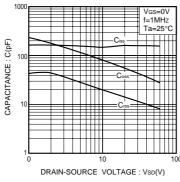


Fig.10 Forward Trasfer Admitance vs. Drain Current

 $\begin{array}{ccc} \text{Fig.11} & \text{Reverse Drain Current vs.} \\ & \text{Source-Drain Voltage}(I) \end{array}$

Fig.12 Reverse Drain Current vs. Source-Drain Voltage(II)





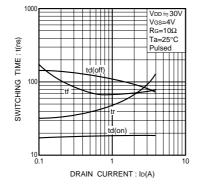


Fig.14 Switching Characteristics (a measurement circuit diagram Fig.17 , it refers 18 times)

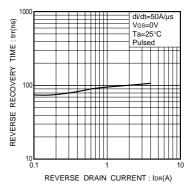


Fig.15 Reverse Recovery Time vs. Reverse Drain Current

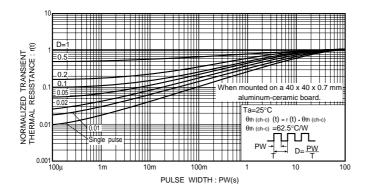
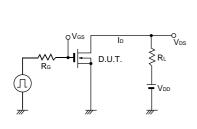


Fig.16 Normarized Transient Thermal Resistance vs. Pulse Width

•Switching characteristics measurement circuit



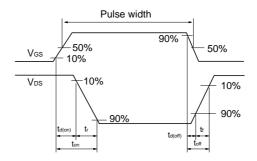


Fig.17 Switching Time Test Circuit

Fig.18 Switching Time Waveforms

Notes

- No technical content pages of this document may be reproduced in any form or transmitted by any
 means without prior permission of ROHM CO.,LTD.
- The contents described herein are subject to change without notice. The specifications for the
 product described in this document are for reference only. Upon actual use, therefore, please request
 that specifications to be separately delivered.
- Application circuit diagrams and circuit constants contained herein are shown as examples of standard
 use and operation. Please pay careful attention to the peripheral conditions when designing circuits
 and deciding upon circuit constants in the set.
- Any data, including, but not limited to application circuit diagrams information, described herein are intended only as illustrations of such devices and not as the specifications for such devices. ROHM CO.,LTD. disclaims any warranty that any use of such devices shall be free from infringement of any third party's intellectual property rights or other proprietary rights, and further, assumes no liability of whatsoever nature in the event of any such infringement, or arising from or connected with or related to the use of such devices.
- Upon the sale of any such devices, other than for buyer's right to use such devices itself, resell or
 otherwise dispose of the same, no express or implied right or license to practice or commercially
 exploit any intellectual property rights or other proprietary rights owned or controlled by
- ROHM CO., LTD. is granted to any such buyer.
- Products listed in this document use silicon as a basic material.
 Products listed in this document are no antiradiation design.

The products listed in this document are designed to be used with ordinary electronic equipment or devices (such as audio visual equipment, office-automation equipment, communications devices, electrical appliances and electronic toys).

Should you intend to use these products with equipment or devices which require an extremely high level of reliability and the malfunction of with would directly endanger human life (such as medical instruments, transportation equipment, aerospace machinery, nuclear-reactor controllers, fuel controllers and other safety devices), please be sure to consult with our sales representative in advance.

About Export Control Order in Japan

Products described herein are the objects of controlled goods in Annex 1 (Item 16) of Export Trade Control Order in Japan.

In case of export from Japan, please confirm if it applies to "objective" criteria or an "informed" (by MITI clause) on the basis of "catch all controls for Non-Proliferation of Weapons of Mass Destruction.

